



# **BERGQUIST HI FLOW THF 1400P**

Known as BERGQUIST HI-FLOW 330P November 2018

#### PRODUCT DESCRIPTION

Electrically Insulating, High Performance. Thermally Conductive Phase Change Material.

| Technology            | Silicone                      |
|-----------------------|-------------------------------|
| Appearance            | Gold                          |
| Reinforcement Carrier | Polyimide                     |
| Total Thickness       | 0.114 to 0.14 mm              |
| Film Thickness        | 0.025 to 0.05 mm              |
| , ASTM D374           |                               |
| Inherent Surface Tack | 1 (1 or 2 side)               |
| Application           | Thermal management,           |
|                       | Thermally conductive adhesive |
| Operating Temperature | -40 to 125°C                  |
| Range                 |                               |

#### **FEATURES AND BENEFITS**

- Thermal impedance: 0.18°C-in²/W @ 25 psi
- Natural tack for ease of assembly
- Exceptional thermal performance in an insulated pad

#### TYPICAL APPLICATIONS

- Spring/clip-mounted devices
- Discrete power semiconductors and modules

BERGQUIST HI FLOW THF 1400P is a thermally conductive phase change material featuring a natural tack on one side and reinforced with a polyimide film. The polyimide film provides a high dielectric strength and cut-through resistance.

BERGQUIST HI FLOW THF 1400P offers excellent handling and consistent liner peel-off characteristics. The material is designed for use between a high power electrical device requiring electrical isolation and its heat sink.

Bergquist recommends the use clips or springs for phase change materials to assure constant pressure between the component interface and the heat sink

#### TYPICAL PROPERTIES

#### **Physical Properties**

| Elongation, ASTM D882,%                  | 40  |
|--|-----|
| Tensile Strength ASTM D882A, psi         |     |
| Phase Change Temperature, ASTM D3418, °C | 52  |
| Flammability Rating, UL 94               | V-0 |

#### **Electrical Properties**

| Dielectric Breakdown Voltage , ASTM D149, Vac | 5,000              |
|---|--------------------|
| Dielectric Constant, ASTM D150 @ 1,000 Hz     | 4.5                |
| Volume Resistivity, ASTM D257, ohm-meter      | 1×10 <sup>12</sup> |

#### **Thermal Properties**

Thermal Conductivity, ASTM D5470, W/(m-K) (1)

#### Thermal Performance vs. Pressure

| iermai Performance vs. Pressure     |      |
|-------------------------------------|------|
| ΓO-220 Thermal Performance, °C/W () |      |
| @ 0.001"                            |      |
| @ 10 psi                            | 1.22 |
| @ 25 psi                            | 1.17 |
| @ 50 psi                            | 1.13 |
| @ 100 psi                           | 1.1  |
| @ 200 psi                           | 1.08 |
| @ 0.0015"                           |      |
| @ 10 psi                            | 1.44 |
| @ 25 psi                            | 1.4  |
| @ 50 psi                            | 1.38 |
| @ 100 psi                           | 1.35 |
| @ 200 psi                           | 1.33 |
| @ 0.002"                            |      |
| @ 10 psi                            | 1.67 |
| @ 25 psi                            | 1.63 |
| @ 50 psi                            | 1.6  |
| @ 100 psi                           | 1.58 |
| @ 100 psi                           | 1.50 |

#### Thermal Impedance, °C/W (2)

@ 200 psi

@ 0.001"

| <u> </u>  |      |
|-----------|------|
| @ 10 psi  | 0.19 |
| @ 25 psi  | 0.18 |
| @ 50 psi  | 0.17 |
| @ 100 psi | 0.16 |
| @ 200 psi | 0.15 |
| @ 0.0015" |      |
| @ 10 psi  | 0.21 |
| @ 25 psi  | 0.21 |
| @ 50 psi  | 0.21 |
| @ 100 psi | 0.19 |
| @ 200 psi | 0.18 |



1.54

| 6 |
|---|
| 6 |
| 4 |
| 3 |
| 2 |
|   |

1) This is the measured thermal conductivity of the Hi-Flow coating. It represents one conducting layer in a three-layer laminate. The Hi-Flow coatings are phase change compounds. These layers will respond to heat and pressure induced stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if additional specifications are required.

2) The ASTM D5470 test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

#### GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

## Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

#### **CONFIGURATIONS AVAILABLE**

BERGQUIST HI FLOW THF 1400P are supplied in:

- Sheet form, roll form and die-cut parts
- Available with 1.0, 1.5 or 2.0 mil Polyimide reinforcement carrier

#### Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

## Disclaimer

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Reference 1

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